IMT-CE06-SF3
ENCAPSULANT EPOXY

IMT-CE06-SF3 is a single component encapsulant epoxy. This product is formulated as a globtop epoxy to protect IC chip for Chip-On-Board and/or Chip-On-Flex applications. It is designed to fast cure at moderate temperature. IMT-CE06-SF3 offers excellent heat, chemical resistance and adhesion properties to PCB and flex-tape.

IMT-CE06-SF3 is non-solvent type and a 100% solid system. It does not contains hazardous, prohibited substances and comply to RoHS3, EU directive 2015/863, Substances of Very High Concern (SVHC) published by ECHA as well as Halogen Free. This product is packed either in syringe or can for automated dispensing.

TYPICAL PROPERTIES*

Cure Conditions	120°C for 40mins 130°C for 20mins
Physical Properties	
Color	Smooth, glossy black before & after cure
Consistency	Flowable paste
Specific Gravity	1.40
Viscosity @1rpm, 25˚C	80,000cPs
Thixotropic Index @0.1/1rpm	2.30
Solid Content	100%
Shore D Hardness	94
Glass Transition Temperature, Tg	133.85°C
CTE below Tg (α1)	55.47ppm
CTE above Tg (α2)	167.30ppm
Water Absorption @100°C-1h	< 0.5%wt
Operating Temperature	-40°C to 150°C
Electrical & Thermal Properties	
Volume Resistivity	> 1 x 10^{13}Ωcm
Thermal conductivity	0.314W/mK
Ionic Contaminants	
Chloride, Cl-	< 650ppm
Bromine, Br-	Not detected
PVC	Not detected
Pot Life	> 4 weeks at room temperature
Shelf Life	18 months at 0°C or below in closed container

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* The information is based on data and tests believed to be accurate. In-Mat Technologies (S) Pte Ltd makes no warranties as to its accuracy and assumes no liability in connection with the use or inability to use this product.